

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3117646

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JAKOB HELANDER	11/20/2014
ZHINONG YING	11/20/2014
RECEIVING PARTY DATA	
Name:	Sony Corporation
Street Address:	1-7-1 Konan
Internal Address:	Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14549574
CORRESPONDENCE DATA	
Fax Number:	(919)854-1401
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9198541400
Email:	mmcmahan@myersbigel.com
Correspondent Name:	MICHELE P. MCMAHAN
Address Line 1:	4140 PARKLAKE AVE. SUITE 600
Address Line 4:	RALEIGH, NORTH CAROLINA 26512
ATTORNEY DOCKET NUMBER:	9342-588/PS14 1528US1
NAME OF SUBMITTER:	MICHELE P. MCMAHAN
SIGNATURE:	/mpm/
DATE SIGNED:	11/21/2014
Total Attachments: 3	
source=9342-588-Assignment#page1.tif	
source=9342-588-Assignment#page2.tif	
source=9342-588-Assignment#page3.tif	

ASSIGNMENT

THIS ASSIGNMENT, made by us, **Jakob Helander**, with a mailing address of Möllevångsvägen 21, Lund, 222 40 Sweden, **Zhinong Ying**, with a mailing address of Fanans Grand 10, Lund, 226 48 Sweden;

WITNESSETH: That,

WHEREAS, we are the joint inventor(s) of certain new and useful improvements in **DUAL BAND MULTI-LAYER DIPOLE ANTENNAS FOR WIRELESS ELECTRONIC DEVICES**, for which an application has been filed, or is being concurrently filed, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 14/549,574, filed 11/21/14) the filing date and application number of said application when known or to file this Assignment concurrently with the application; and

WHEREAS, Sony Corporation, a corporation organized under the laws of Japan, having a principal place of business at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075 Tokyo, Japan, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

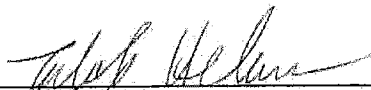
NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer, and convey unto the said assignee, its successors and assigns, the entire right, title, and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues or other forms of protection thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted along with any term extensions thereon or therefor, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

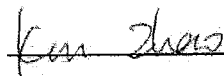
We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to promptly communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors, or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns, and other legal representatives; and we hereby instruct, and further covenant and agree to bind our heirs, legal representatives, and assigns, to do same, without further compensation, but at the expense of said assignee or its representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 20th day of November, 2014.

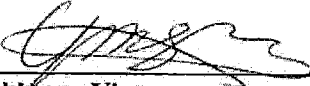
 (SEAL)
Jakob Helander

Witnessed by:



Date: 2014-11-20

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 20th day of
Nov., 2014.



Zhinong Ying (SEAL)

Witnessed by:

Kun Zhao

Date: 2014-11-20